LED Power Supply Potting
IRS2040-1

Application

Potting of electronic components and power supply of specialist LED displays.

Substrates bonded	ABS and FR4
Process	Potting
Pre-treatment	None
Curing conditions	▪ 20°C for 48 hours
Resistances required	▪ Water resistance due to outdoor use
Key selection criteria	▪ Low coefficient of thermal expansion ▪ Thermally conductive
Customer benefits	▪ CTE of 35-55 ppm/°C reduces potential stress placed on potted PCBs during outdoor temperature fluctuation ▪ Minimal water absorption (0.3%/30 days) protects sensitive electronics from moisture ▪ Thermally conductive potting compound dissipates heat to improve component reliability ▪ Cures at room temperature without need of curing ovens

Product description

IRS 2040-1 Epoxy Potting Compound is a non-toxic general-purpose flame-retardant encapsulating compound. It has a long pot life and can be cured at ambient temperatures or accelerated with heat.

Features and benefits:

- High electrical insulating characteristics
- Good thermal conductivity
- Low shrinkage
- High adhesion
- Flame retardant to UL94 V-0 @ 3mm
- Good chemical and water resistance
- Long pot life
- Cured at room temperature or with heat

Suitable in applications involving:

- Electronics potting in harsh environments
- Vehicle electronics
- Pipeline inspection systems

Let's start by talking about your application
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